

CHIPMOS TECHNOLOGIES BERMUDA LTD

Form 6-K

June 25, 2013

# **SECURITIES AND EXCHANGE COMMISSION**

**Washington, DC 20549**

## **FORM 6-K**

**REPORT OF FOREIGN PRIVATE ISSUER  
PURSUANT TO RULE 13a-16 OR 15d-16 OF  
THE SECURITIES EXCHANGE ACT OF 1934**

**For the month of June, 2013**

### **ChipMOS TECHNOLOGIES (Bermuda) LTD.**

**(Translation of Registrant's Name Into English)**

**No. 1, R&D Rd. 1, Hsinchu Science Park**

**Hsinchu, Taiwan**

**Republic of China**

**(Address of Principal Executive Offices)**

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(Indicate by check mark whether the registrant files or will file annual reports under cover of Form 20-F or Form 40-F.)

Form 20-F  Form 40-F

(Indicate by check mark whether the registrant by furnishing the information contained in this form is also thereby furnishing the information to the Commission pursuant to Rule 12g3-2(b) under the Securities Exchange Act of 1934.)

Yes  No

(If  Yes is marked, indicate below the file number assigned to the registrant in connection with Rule 12g3-2(b): 82- .)

**SIGNATURES**

Pursuant to the requirements of the Securities Exchange Act of 1934, the registrant has duly caused this report to be signed on its behalf by the undersigned, thereunto duly authorized.

ChipMOS TECHNOLOGIES (Bermuda) LTD.  
(Registrant)

Date: June 25, 2013

By /s/ S. J. Cheng  
Name: S. J. Cheng  
Title: Chairman & Chief Executive Officer

**Contacts:**

In Taiwan

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**ChipMOS SETTLES WITH FREESCALE ON THE DISPUTE OF**

**TECHNOLOGY IMMUNITY AGREEMENT**

**Hsinchu, Taiwan, June 25, 2013** - ChipMOS TECHNOLOGIES, INC. ( ChipMOS Taiwan ), an 83.45% owned subsidiary of ChipMOS TECHNOLOGIES (Bermuda) LTD. ( ChipMOS or the Company ) entered into a settlement agreement (the Agreement ) with Freescale Semiconductor, Inc. ( Freescale ). Under the Agreement, ChipMOS Taiwan will pay Freescale US\$8 million on or before July 20, 2013 to settle all claims in the currently pending lawsuit between the two parties pursuant to the Agreement. Additionally, Freescale shall grant ChipMOS Taiwan a Ball Grid Array ( BGA ) package license. As consideration, ChipMOS Taiwan shall make license fee payments to Freescale through 2015. The two parties will enter into a detailed settlement agreement and a BGA package license agreement in accordance with the Agreement on or before July 20, 2013.

**Forward-Looking Statements**

Certain statements contained in this announcement may be viewed as forward-looking statements within the meaning of Section 27A of the U.S. Securities Act of 1933, as amended, and Section 21E of the U.S. Securities Exchange Act of 1934, as amended. Such forward-looking statements involve known and unknown risks, uncertainties and other factors, which may cause the actual performance, financial condition or results of operations of the Company to be materially different from any future performance, financial condition or results of operations implied by such forward-looking statements. Further information regarding these risks, uncertainties and other factors is included in the Company's most recent Annual Report on Form 20-F filed with the U.S. Securities and Exchange Commission (the SEC ) and in the Company's other filings with the SEC.